

Abstract**Method for Grinding Semiconductor Wafers**

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The present invention relates to a method for grinding semiconductor wafers, the semiconductor wafers being processed so as to remove material on one or both sides by means of at least one grinding tool, respectively with supply of a coolant into a contact region between the semiconductor wafer and the at least one grinding tool, characterized in that the coolant flow rate is respectively selected as a function of a grinding tooth height of the at least one grinding tool and this coolant flow rate is reduced as the grinding tooth height decreases.

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(No figure)